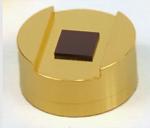
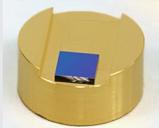


SAM™ Data Sheet SAM-1030-20-30ps-30-x

	Minimum	Typical Value	Maximum
Operational wavelength λ		1030 nm	
High reflection band	1020 nm		1040 nm
Absorbance A	16 %	20 %	24 %
Modulation depth ΔR	10 %	13 %	
Saturation fluence Φ_{sat}	15 $\mu\text{J}/\text{cm}^2$	30 $\mu\text{J}/\text{cm}^2$	50 $\mu\text{J}/\text{cm}^2$
Relaxation time constant τ	15 ps	30 ps	50 ps
Damage threshold Φ		800 $\mu\text{J}/\text{cm}^2$	
Absorber Peak Temperature			150°C ¹
Chip thickness	425 μm	450 μm	475 μm
Protection	SAM is protected with a dielectric front layer		

¹ One has to make sure that this temperature is not exceeded in pulsed operation at any time.

Mounting Options SAM-1030-20-30ps-30	Description
SAM-1030-20-30ps-30-4.0-0	Single chip, unmounted, chip size 4.0mm x 4.0mm
SAM-1030-20-30ps-30-1.0b-0	Batch of 4 unmounted chips, chip size 1.0mm x 1.0mm
SAM-1030-20-30ps-30-1.3b-0	Batch of 4 unmounted chips, chip size 1.3mm x 1.3mm
SAM-1030-20-30ps-30-4.0-12.7g-c SAM-1030-20-30ps-30-4.0-12.7g-e	chip size 4.0mm x 4.0mm, glued on a gold plated Cu-cylinder with 12.7 mm \varnothing
SAM-1030-20-30ps-30-4.0-25.0g-c SAM-1030-20-30ps-30-4.0-25.0g-e	chip size 4.0mm x 4.0mm, glued on a gold plated Cu-cylinder with 25.0 mm \varnothing
SAM-1030-20-30ps-30-4.0-25.4g-c SAM-1030-20-30ps-30-4.0-25.4g-e	chip size 4.0mm x 4.0mm, glued on a gold plated Cu-cylinder with 25.4 mm \varnothing
SAM-1030-20-30ps-30-4.0-12.7s-c SAM-1030-20-30ps-30-4.0-12.7s-e	chip size 4.0mm x 4.0mm, soldered on a gold plated Cu-cylinder with 12.7 mm \varnothing
SAM-1030-20-30ps-30-4.0-25.0s-c SAM-1030-20-30ps-30-4.0-25.0s-e	chip size 4.0mm x 4.0mm, soldered on a gold plated Cu-cylinder with 25.0 mm \varnothing
SAM-1030-20-30ps-30-4.0-25.4s-c SAM-1030-20-30ps-30-4.0-25.4s-e	chip size 4.0mm x 4.0mm, soldered on a gold plated Cu-cylinder with 25.4 mm \varnothing
SAM-1030-20-30ps-30-4.0-25.0w-c SAM-1030-20-30ps-30-4.0-25.0w-e	chip size 4.0mm x 4.0mm, soldered on a water cooled copper heat sink with 25.0 mm diameter
SAM-1030-20-30ps-30-4.0-25.4h-c SAM-1030-20-30ps-30-4.0-25.4h-e	chip size 4.0mm x 4.0mm, thin film soldered on a water cooled copper heat sink with 25.0 mm diameter for high power application
 <p>-c Center mounting</p>	 <p>-e Edge mounting</p>
SAM-1030-20-30ps-30-FC/APC-SMF SAM-1030-20-30ps-30-FC/PC-SMF	mounted on a 1 m long single mode fiber (HI1060) - FC/PC connector: x = FC/PC-SMF - FC/APC connector: x = FC/APC-SMF
SAM-1030-20-30ps-30-FC/APC-PMF SAM-1030-20-30ps-30-FC/PC-PMF	mounted on a 1 m long polarization maintaining single mode fiber (SM98-PS-U25D) - FC/PC connector: x = FC/PC-PMF - FC/APC connector: x = FC/APC-PMF
Other chip dimensions are also possible, please ask.	